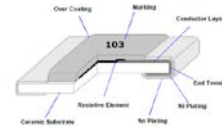


MATERIAL DECLARATION SHEET



Material Number	CR0805 Series		
Product Line	Thick Film Chip Resistors		
Compliance Date	04-01-2003		
RoHS Compliant	Yes	MSL	1



No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00382	Aluminum oxide	1344-28-1	96%	85.56	89.13
				Silicon dioxide	14808-60-7	4%	3.57	
2	Conductor Layer	Thick Film Conductor	0.000083	Silver	7440-22-4	96%	1.84	1.92
				Bismuth	7440-69-9	1%	0.02	
				Barium	7440-39-3	1%	0.02	
				Silicon	7440-21-3	1%	0.02	
				Boron	7440-42-8	1%	0.02	
3	Resistive Element	Thick Film Resistor	0.000043	Ruthenium dioxide	12036-10-1	25%	0.25	1.01
				Silver	7440-22-4	40%	0.4	
				Palladium	7440-05-3	15%	0.15	
				Lead	7439-92-1	20%	0.2	
4	Over Coating	Epoxy	0.000067	Epoxy	29690-82-2	100%	1.55	1.55
5	Marking	Epoxy	0.0000036	Epoxy	25085-99-8	100%	0.08	0.08
6	End Terminal	NI-CR	0.0000034	Nickel	7440-02-0	80%	0.06	0.08
				Chromium	7440-47-3	20%	0.02	
7	Ni Plating	Nickel	0.00014	Nickel	7440-02-0	100%	3.29	3.29
8	Sn Plating	Tin	0.00013	Tin	7440-31-5	100%	2.94	2.94
			Total weight	0.00429				

This Document was updated on: **2016-2-5**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I.